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(71) Applicant: SONY CORP

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(54) WAFER, IDENTIFICATION INFORMATION READING METHOD, METHOD AND APPARATUS FOR MANUFACTURING INTEGRATED CIRCUIT

(57) Abstract:

PURPOSE: To deal with a multikind and small quantity production by setting optimum step conditions for each one wafer.

CONSTITUTION: A step in a process managing list 12 is updated to a next step based on identification information on a wafer 16 read by an identification information reader 14 under the control of a centralized controller 11. A process condition corrector 19 retrieves a past inspection result from a process data base 21 according to a run command from the controller 11 for the next step, processes the wafer 16 by a processor M in a processing section 15 for the next step if the retrieved result is satisfied, and then inspect it by an inspecting unit T in an inspecting section 18. This inspected result is cataloged with a process data base 21 from the corrector 19.